WWSTE46N100

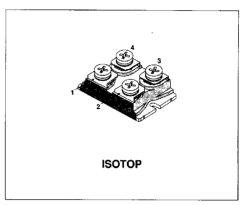
N - CHANNEL ENHANCEMENT MODE POWER MOS TRANSISTOR IN ISOTOP PACKAGE

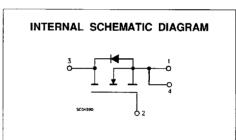
TYPE	Voss	R _{DS(on)}	l _D
STE16N100	1000 V	< 0.7 Ω	16 A

- HIGH CURRENT POWER MODULE
- AVALANCHE BUGGED TECHNOLOGY (SEE STH6N100 FOR RATING)
- VERY LARGE SOA LARGE PEAK POWER CAPABILITY
- EASY TO MOUNT
- SAME CURRENT CAPABILITY FOR THE TWO SOURCE TERMINALS
- EXTREMELY LOW Rth JUNCTION TO CASE
- VERY LOW DRAIN TO CASE CAPACITANCE
- VERY LOW INTERNAL PARASITIC INDUCTANCE (TYPICALLY < 5 nH)
- ISOLATED PACKAGE UL RECOGNIZED (FILE No E81743)

INDUSTRIAL APPLICATIONS:

- SMPS & UPS
- MOTOR CONTROL
- WELDING EQUIPMENT
- OUTPUT STAGE FOR PWM, ULTRASONIC **CIRCUITS**





ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{DS}	Drain-Source Voltage (V _{GS} = 0)	1000	٧
V _{DGR}	Drain-Gate Voltage (R _{GS} = 20 kΩ)	1000	٧
V_{GS}	Gate-Source Voltage	± 20	٧
ΙD	Drain Current (continuous) at T _c = 25 °C	16	Α
ID	Drain Current (continuous) at T _c = 100 °C	10	Α
I _{DM} (•)	Drain Current (pulsed)	64	Α
P _{tot}	Total Dissipation at T _c = 25 °C	400	W
	Derating Factor	3.2	W/°C
T _{stg}	Storage Temperature	www.BataSheet4U.com	°C
Tj	Max. Operating Junction Temperature	150	°C
V _{ISO}	Insulation Withstand Voltage (AC-RMS)	2500	٧

(•) Pulse width limited by safe operating area

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STE16N100

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IHEKWAL	DATAFor	Evaluat	ion C	nly.

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R _{thj-case}	Thermal Resistance Junction-case	Max	0.31	°C/W
R _{thc-h}	Thermal Resistance Case-heatsink With Conductive Grease Applied	Max	0.05	°C/W

ELECTRICAL CHARACTERISTICS (T_{case} = 25 °C unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source Breakdown Voltage	I _D = 1 mA V _{GS} = 0 V	1000			٧
loss	Zero Gate Voltage Drain Current (V _{GS} = 0)	V_{DS} = Max Rating V_{DS} = Max Rating x 0.8 T_c = 125 °C			300 1.5	μA mA
lgss	Gate-body Leakage Current (V _{DS} = 0)	V _{GS} = ± 20 V			± 300	nA

ON (*)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} I _D = 1 mA	2		4	V
R _{DS(on)}	Static Drain-source On Resistance	V _{GS} = 10V I _D = 9 A			0.7	Ω

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g _{fs} (*)	Forward Transconductance	V _{DS} = 15 V I _D = 9 A	8			S
Ciss Coss Crss	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}$ f = 1 MHz $V_{GS} = 0 \text{ V}$			7 850 250	nF pF pF

SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r	Turn-on Time Rise Time	V_{DD} = 500 V I_D = 9 A R_G = 4.7 Ω V_{GS} = 10 V (see test circuit, figure 1)		65 78		ns ns
(di/dt) _{on}	Turn-on Current Slope	$V_{DD} = 800 \text{ V}$ $I_D = 16 \text{ A}$ $R_G = 4.7 \Omega$ $V_{GS} = 10 \text{ V}$ (see test circuit, figure 3)		570		A/μs
Qg	Total Gate Charge	V _{DD} = 800 V I _D = 16 A V _{GS} = 10 V		375		nC

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ELECTRICAL CHARACTEFESTE QSa (COUNTINGED).

SWITCHING OFF

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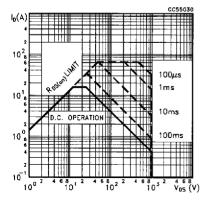
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{r(Voff)}	Off-voltage Rise Time	V _{DD} = 800 V I _D = 16 A		75	95	ns
tf	Fall Time	$R_G = 4.7 \Omega$ $V_{GS} = 10 V$	1	20	28	ns
tc	Cross-over Time	(see test circuit, figure 3)	1	112	144	ns

SOURCE DRAIN DIODE

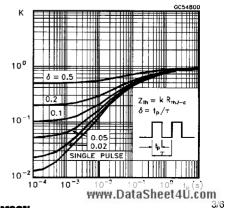
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I _{SD} I _{SDM} (●)	Source-drain Current Source-drain Current (pulsed)				16 64	A A
V _{SD} (*)	Forward On Voltage	I _{SD} = 16 A V _{GS} = 0			2.5	٧
t _{rr}	Reverse Recovery Time	I _{SD} = 16 A di/dt = 100 A/μs V _{DD} = 100 V T _i = 150 °C		1250		ns
Q_{rr}	Reverse Recovery Charge	(see test circuit, figure 3)		37		μC
I _{RRM}	Reverse Recovery Current			59		Α

^(*) Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %

Safe Operating Area



Thermal Impedance

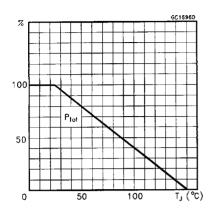


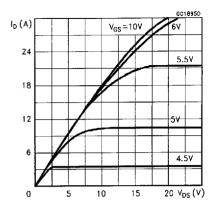
^(•) Pulse width limited by safe operating area

STE16N100

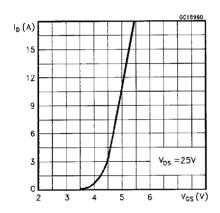
Derating Curve

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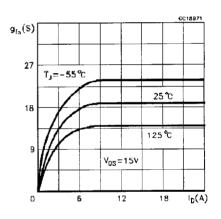




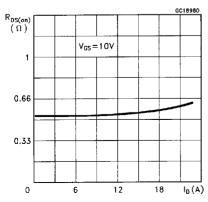
Transfer Characteristics



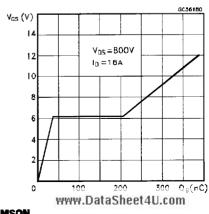
Transconductance



Static Drain-source On Resistance

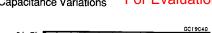


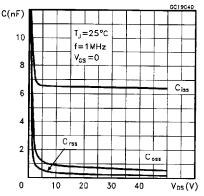
Gate Charge vs Gate-source Voltage



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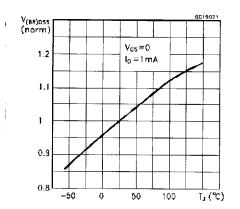
Capacitance Variations



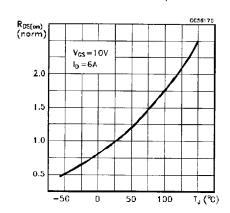


Temperature V_{CS(Ih)} (norm) Vos=Vos $I_D = 1 \, \text{mA}$ 1.1 1.0 0.9 0.8 0.7 -50 n 50 100

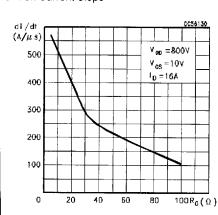
Normalized Breakdown Voltage vs Temperature



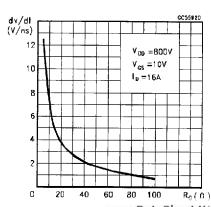
Normalized On Resistance vs Temperature



Turn-on Current Slope



Turn-off Drain-source Voltage Slope



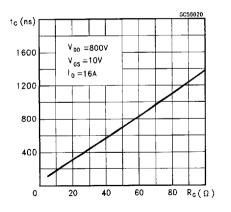
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Source-drain Diode Forward Character

Cross-over Time

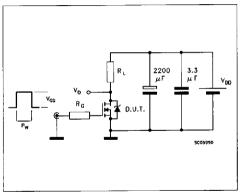
Source-drain Diode Forward Characteristics



I_{SD}(A) T₁=150°C 25°C V_{GS}=0 101 10 2 V_{SD}(V)

Fig. 1: Switching Times Test Circuits For Resistive Load

Fig. 2: Gate Charge Test Circuit



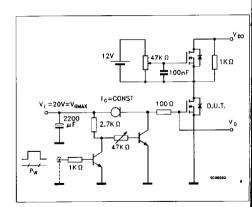


Fig. 3: Test Circuit For Inductive Load Switching And Diode Recovery Times

